

ABSTRACT OF THE DISCLOSURE

A method for forming bumps in an LSI package in which: semiconductor chips are mounted onto a flexible printed circuit board; electrically conductive balls are temporarily fixed by using electrically conductive paste selected from flux, solder paste and a fixing liquid containing an electrically conductive adhesive agent, onto pads which are provided on the flexible printed circuit board so as to be electrically connected to the semiconductor chips; the flexible printed circuit board having the electrically conductive balls temporarily fixed thereto is wound up onto a reel; the flexible printed circuit board having the electrically conductive balls temporarily fixed thereto is fed out from the reel and heated to thereby form bumps thereon; and the flexible printed circuit board having the bumps formed thereon is wound up onto another reel; and the flexible printed circuit board is cleansed and trimmed to thereby form LSI packages.

